

WEST Search History for Application 10589912

Creation Date: 2009030610:31

Query	DB
374/170	USPT
(374/120,121;250/338.1)! [CCLS]	PGPB, USPT, USOC, EPAB, JPAB
((374/120,121;250/338.1)! [CCLS]) and (semiconductor near circuit or integrated circuit or circuit board or PCB)	PGPB, USPT, USOC, EPAB, JPAB
((374/120,121;250/338.1)! [CCLS] and (semiconductor near circuit or integrated circuit or circuit board or PCB)) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or thermal camera or thermograph\$3 or thermal scan\$4)	PGPB, USPT, USOC, EPAB, JPAB
((374/120,121;250/338.1)! [CCLS] and (semiconductor near circuit or integrated circuit or circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or thermal camera or thermograph\$3 or thermal scan\$4)) and (heat sink or spreader or cooling or coolant)	PGPB, USPT, USOC, EPAB, JPAB
((374/120,121;250/338.1)! [CCLS] and (semiconductor near circuit or integrated circuit or circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or thermal camera or thermograph\$3 or thermal scan\$4)) and (heat sink)	PGPB, USPT, USOC, EPAB, JPAB
((374/120,121;250/338.1)! [CCLS] and (semiconductor near circuit or integrated circuit or circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or thermal camera or thermograph\$3 or thermal scan\$4)) and (control\$3 or regulat\$3 or adjust\$3 or power near remov\$3)	PGPB, USPT, USOC, EPAB, JPAB
((374/120,121;250/338.1)! [CCLS] and (semiconductor near circuit or integrated circuit or circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or thermal camera or thermograph\$3 or thermal scan\$4)) and (power near control\$3 or power near regulat\$3 or power near adjust\$3 or power near remov\$3)	PGPB, USPT, USOC, EPAB, JPAB
(374/170 and (verbitsky) and (integrated circuit)) and (bowden)	PGPB, USPT,

	USOC, EPAB, JPAB
((374/120,121;250/338.1)! [CCLS] and (semiconductor near circuit or integrated circuit or circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or thermal camera or thermograph\$3 or thermal scan\$4) and (control\$3 or regulat\$3 or adjust\$3 or power near remov\$3)) and (overheat\$3)	PGPB, USPT, USOC, EPAB, JPAB
(374/121,120,170,29,137,4,5,43,44,45,57,100,112;250/338.1;702/130,131,132,133,134,135,136)! [CCLS]	PGPB, USPT, USOC, EPAB, JPAB
((374/121,120,170,29,137,4,5,43,44,45,57,100,112;250/338.1;702/130,131,132,133,134,135,136)! [CCLS]) and (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board)	PGPB, USPT, USOC, EPAB, JPAB
((374/121,120,170,29,137,4,5,43,44,45,57,100,112;250/338.1;702/130,131,132,133,134,135,136)! [CCLS] and (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board)) and (thermal camera or thermal imag\$3 or thermal scan\$\$ or infrared camera or infrared imag\$3 or infrared scan\$3 or thermograph\$4 or radiation near detect\$3 or infrared near sens\$3 or infrared near detect\$3 or IR camera)	PGPB, USPT, USOC, EPAB, JPAB
(testing or examin\$4 or inspect\$3 or test or NDE or nondestructiv\$4 or DUT or device under test) same (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board)	PGPB, USPT, USOC, EPAB, JPAB
((testing or examin\$4 or inspect\$3 or test or NDE or nondestructiv\$4 or DUT or device under test) same (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board)) and ((374/121,120,170,29,137,4,5,43,44,45,57,100,112;250/338.1;702/130,131,132,133,134,135,136)! [CCLS])	PGPB, USPT, USOC, EPAB, JPAB
((testing or examin\$4 or inspect\$3 or test or NDE or nondestructiv\$4 or DUT or device under test) same (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board) and (374/121,120,170,29,137,4,5,43,44,45,57,100,112;250/338.1;702/130,131,132,133,134,135,136)! [CCLS]) and (thermal camera or thermal imag\$3 or thermal scan\$\$ or infrared camera or infrared imag\$3 or infrared scan\$3 or thermograph\$4 or radiation near detect\$3 or infrared near sens\$3 or infrared near detect\$3 or IR camera)	PGPB, USPT, USOC, EPAB, JPAB
((testing or examin\$4 or inspect\$3 or test or NDE or nondestructiv\$4 or DUT or device under test) same (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board) and (374/121,120,170,29,137,4,5,43,44,45,57,100,112;250/338.1;702/130,131,132,133,134,135,136)! [CCLS] and (thermal camera or thermal imag\$3 or thermal scan\$\$ or infrared camera or infrared imag\$3 or infrared scan\$3 or thermograph\$4 or radiation near detect\$3 or infrared near sens\$3 or infrared near detect\$3 or IR camera)) and (power near control\$3 or power near regulat\$3 or power near adjust\$3 or	PGPB, USPT, USOC, EPAB, JPAB

power near remov\$3)
